Novel High Temperature Electronics Packaging

As the hybrid electric vehicle market and worldwide power grid undergo significant expansion, the need for robust packaging solutions for high power electronics has increased dramatically. As a result a growing use of silicon carbide and gallium nitride wide band gap semiconductors has resulted.

University of Arkansas researchers have developed a lead-free, low cost, novel electronics packaging and attachment process that supports large area substrate attachments with electrical and thermal stability at or above 300 degrees Celsius. The approach supports hostile operating environments in automotive applications, defense electronics, and power grid related systems.

This technology is currently pre-patent and to get further information a nondisclosure agreement will be required. The invention is available for licensing through the University of Arkansas Technology Licensing Office.

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